

Electrical and Acoustical Parameter

Rated voltage (VDC) *	3.0
Operating voltage (VDC)	2.0 – 5.0
Rated current (mA) *	max. 30
Sound pressure level (dBA/10cm) *	min. 83
Resonant Frequency (Hz±300)	2400

Remark:

*Applying rated voltage

Mechanical, Environmental Parameter

Contact / Wire	Pin
Operating temperature (°C)	-40 to +85
Storage temperature (°C)	-40 to +85
Material housing	PPO
Color housing	Black
Component weight (g)	1.6

Remark:

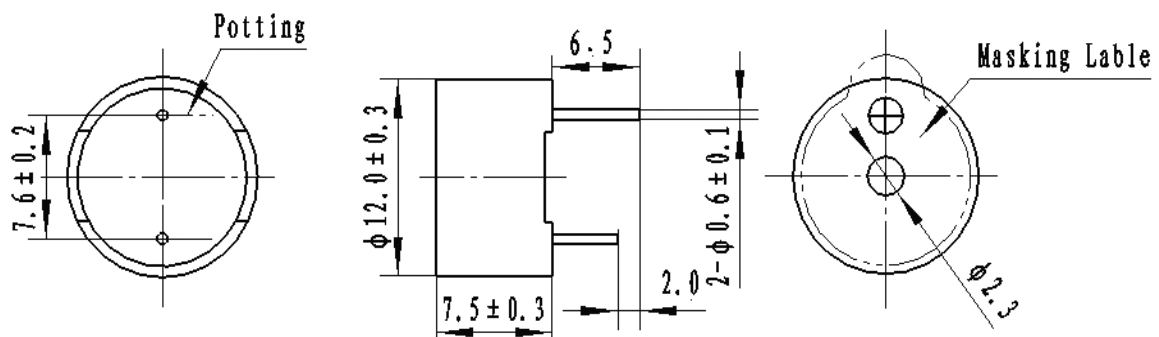
Approval

RoHs

UL

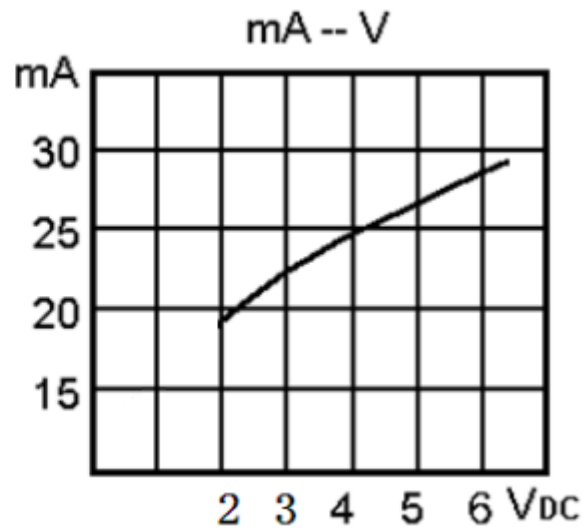
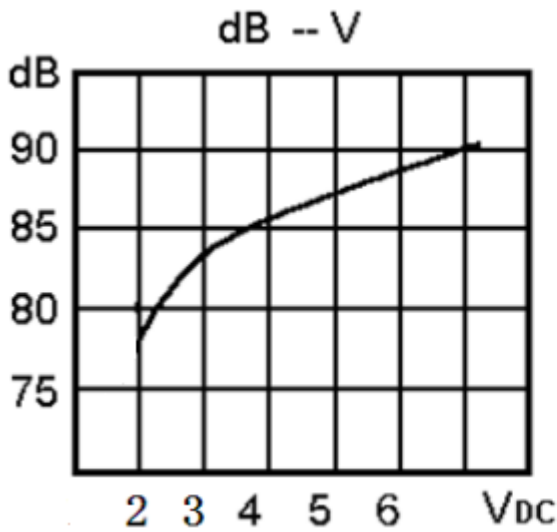
Drawing of Component

Unit:mm

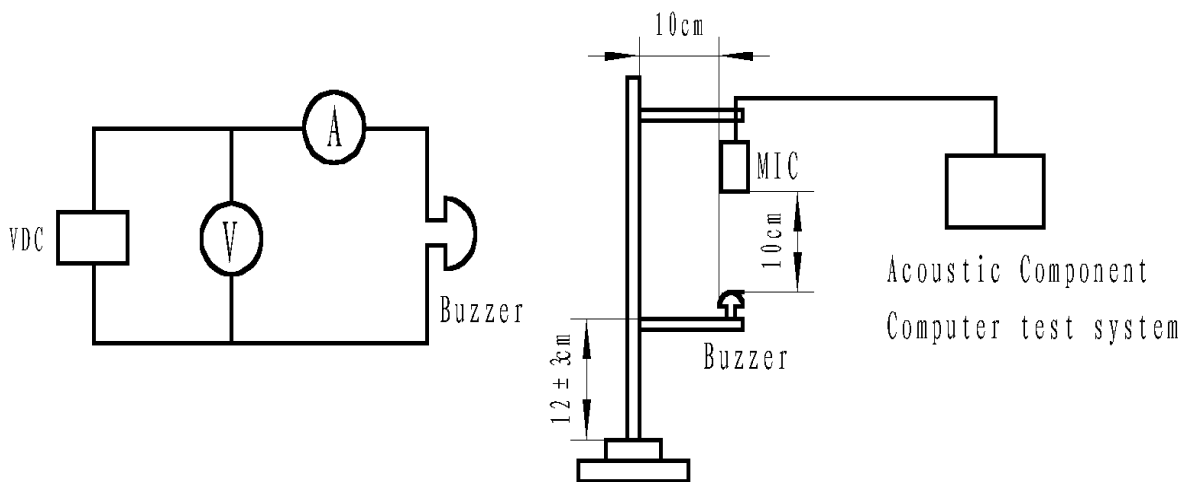


Designed by	KH	21.11.2011	Dimensions without tolerance ± 0.5 mm	Index: 03	Current date
Released by	BB	21.11.2011	Drawing number	111121.1PDB	01.03.2016
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Input Voltage VS. Sound Pressure Level & Current Consumption



Test Method



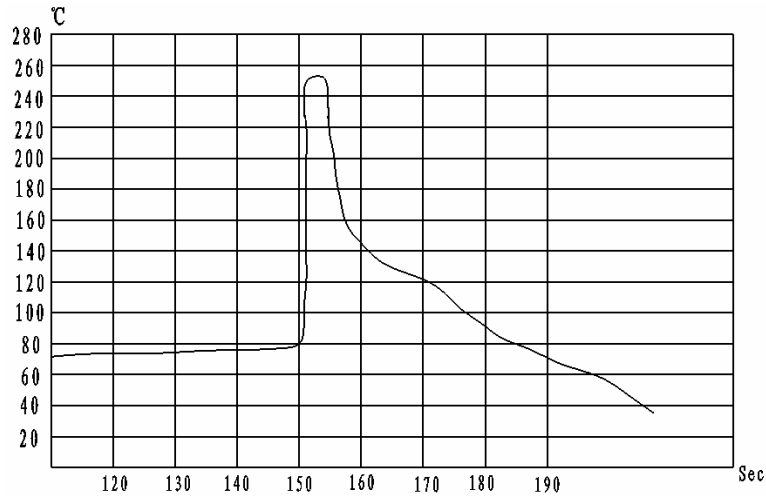
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Reliability Test

NO.	ITEM	TESTING CONDITION	VARIANCE AFTER TEST
1	Humidity	Testing condition 40±5°C, 93(+2/-3)%RH, 96HRS	All specifications must be satisfied after the test.
2	High temp.	+80±2°C, 96HRS	
3	Low temp.	-30±2°C, 96HRS	
4	Temperature cycling	-30±2°C, 30 minutes room temp. 15 minutes +80±2°C, 30 minutes room temp. 15 minutes 5 cycles	
5	Drop test	3 times from height of 70cm onto the surface of 10mm thick wooden board.	
6	Vibration test	Make the test for the directions of X Y and Z (total 0.5 hours). To-and-fro sweep time (from 10 to 55 Hz and then 55 to 10) under single amplitude of 1.0mm is 1 minute	
7	Solder heat resistance	The part leads (pins) shall be immersed in molten solder maintained at 250±10°C for a period of 30 seconds.	

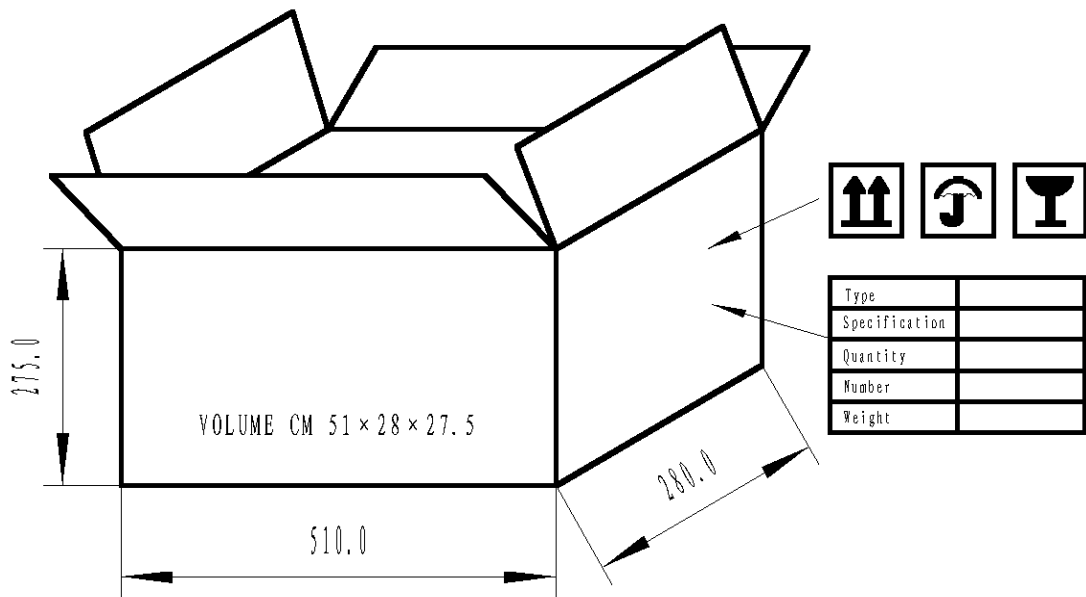
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Recommended Temp. Profile for Reflow Oven (Fig.1)



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Packaging Information



NOTES:

- 1.100 PCS per box
- 2.Total 30 boxes per carton
- 3.Total 3000 PCS carton
- 4.Volume:51x28x27.5cm

Revision Table

Index Nr.	Date Reason - Procedure Change description	Drawing Date	implementation	Comments
			LS-Nr.: Date	
01	Add solder profile	29.08.2012	29.08.2012	
02	New temperature range	15.07.2013	15.07.2013	
03	SPL, Frequency, Weight	01.03.2016	01.03.2016	

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